

Amendments to the Specification

Please amend the title as follows

~~ELECTRICAL WIRING OF SEMICONDUCTOR DEVICE AND~~ METHOD OF
MANUFACTURING SEMICONDUCTOR DEVICE

Please amend the paragraph beginning at page 1, line 5 as follows:

This application is a divisional application of U.S. Patent Application Serial No.
09/637,066, which is based upon Japanese Patent Application No. Hei. 11-234272 filed on
August 20, 1999, the contents of which are incorporated herein by reference.